

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S36	9	S35 not (S1 S4 S8 S14 S25)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:47
S37	3579	(257/778-779).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 19:47
S38	67	S37 and (attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)with (IC integrated near1 circuit chip microelectronic die semiconductor) with (angle slop\$3 inclinat\$ diagonal\$3 not near2 parallel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 20:14
S39	30	S38 not (S1 S4 S8 S14 S25 S35)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:48
S43	2499	((attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)and (IC integrated near1 circuit chip microelectronic die semiconductor) and (diagonal\$3 angle slop\$3 inclinat\$ diagonal\$3 not near2 parallel) and (substrate board bga pcb interposer tape insulat\$3 near1 layer)).clm.	US-PGPUB US-PGPUB	OR	ON	2006/03/01 20:15
S44	54047	((attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)and(IC integrated near1 circuit chip microelectronic die semiconductor) and (solder bump ball c4 contact electrode) and (substrate board bga pcb interposer tape insulat\$3 near1 layer)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 20:16
S45	20025	((attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)and(IC integrated near1 circuit chip microelectronic die semiconductor) and (solder bump ball c4 contact electrode) and (substrate board bga pcb interposer tape insulat\$3 near1 layer)).clm.	US-PGPUB	OR	ON	2006/03/01 20:17

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S46	2059	((attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)and(IC integrated near1 circuit chip microelectronic die semiconductor) and (solder bump ball c4 contact electrode) and (substrate board bga pcb interposer tape insulat\$3 near1 layer) and (seal\$3 underfill)).clm.	US-PGPUB	OR	ON	2006/03/01 20:27
S48	273	((attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)and(IC integrated near1 circuit chip microelectronic die semiconductor) and (solder bump ball c4) and (substrate board bga pcb interposer tape insulat\$3 near1 layer) and (underfill)).clm.	US-PGPUB	OR	ON	2006/03/01 20:38
S49	1	("20040047539" "3811186" "5056215" "5173220" "5220200" "5278442" "5484314" "5700715" "5705117" "6251488" "6259962" "6268584" "6287895" "6301251" "6326698" "6410366" "6461881" "6506671" "6525408" "6544821" "6548897" "6569753" "6630385" "6649444" "6740962").PN.	US-PGPUB	OR	ON	2006/03/01 20:27
S50	25	("20040047539" "3811186" "5056215" "5173220" "5220200" "5278442" "5484314" "5700715" "5705117" "6251488" "6259962" "6268584" "6287895" "6301251" "6326698" "6410366" "6461881" "6506671" "6525408" "6544821" "6548897" "6569753" "6630385" "6649444" "6740962").PN.	US-PGPUB; USPAT	OR	ON	2006/03/01 20:27
S51	32	("20020185746" "20030022462" "20030045028" "3811186" "5056215" "5173220" "5264061" "5278442" "5484314" "5633535" "5705117" "5841198" "6140707" "6165885" "6255143" "6281577" "6313522" "6313650" "6316286" "6358776" "6399421" "6420213" "6440774" "6444489" "6461881").PN. OR ("6649444").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 20:36
S52	15	("3811186" "5056215" "5173220" "5264061" "5278442" "5484314" "5633535" "5705117" "5841198" "6140707" "6165885" "6255143" "6281577" "6313522" "6313650").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 20:58
S53	151	and\$1j\$2.xa.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 20:58
S54	3	("5115545" "6269999" "6559523").PN. OR ("6978534").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 20:59

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S55	20	("2756483" "3204327" "3657790" "3729966" "3811182" "3946484" "4095095" "4340617" "4718967" "4749120").PN. OR ("5115545"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 21:00
S56	25	("4831724" "5037780" "5115545" "5205032" "5214308" "5232532" "5316610" "5385632" "5722160" "5739053" "5785234" "5802712" "5813115" "5816478" "5829125").PN. OR ("6000127"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 21:03
S57	3	("6069024" "6404062" "6576495"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 21:03
S58	12	("5962925").PN. OR ("6069024"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 21:12
S59	1	"20020043711".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 21:12